

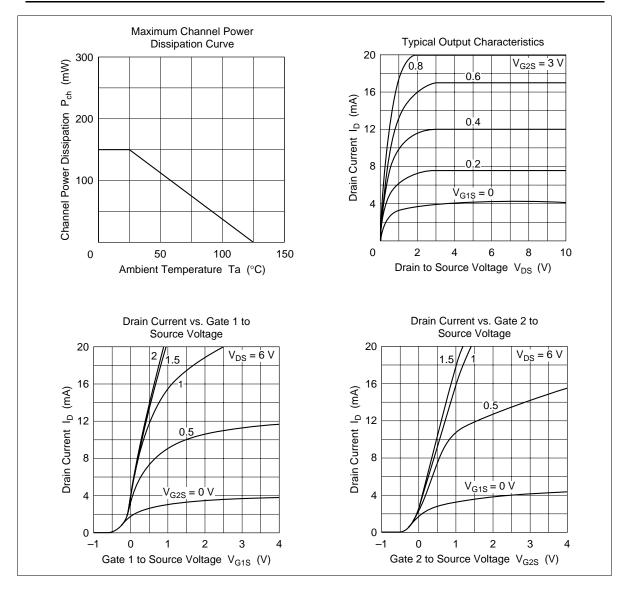
Absolute Maximum Ratings (Ta = 25° C)

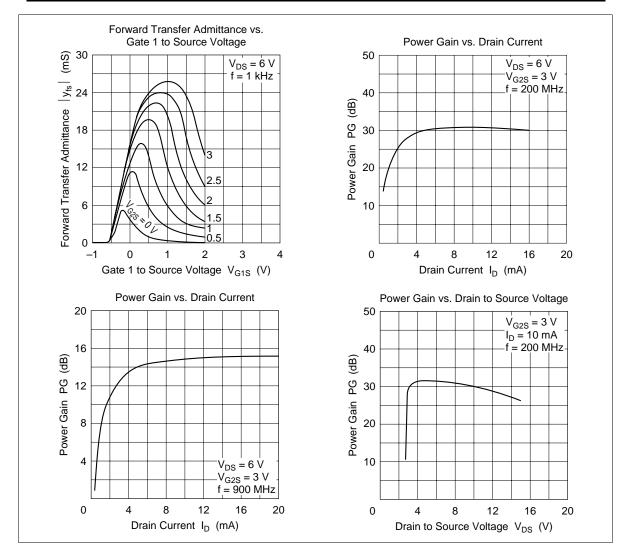
Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	15	V	
Gate 1 to source voltage	V _{G1S}	±10	V	
Gate 2 to source voltage	V _{G2S}	±10	V	
Drain current	I _D	35	mA	
Channel power dissipation	Pch	150	mW	
Channel temperature	Tch	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Electrical Characteristics (Ta = 25°C)

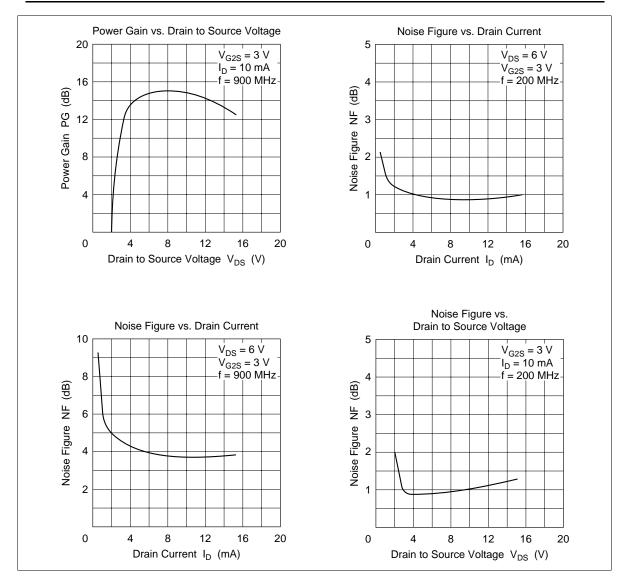
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSX}$	15			V	$I_{_{D}} = 200 \ \mu A,$ $V_{_{G1S}} = V_{_{G2S}} = -5 \ V$
Gate 1 to source breakdown voltage	$V_{\rm (BR)G1SS}$	±10	—	_	V	$I_{G1} = \pm 10 \ \mu A, \ V_{G2S} = V_{DS} = 0$
Gate 2 to source breakdown voltage	$V_{(BR)G2SS}$	±10	—	_	V	$I_{G2} = \pm 10 \ \mu A, \ V_{G1S} = V_{DS} = 0$
Gate 1 cutoff current	I _{G1SS}		—	±100	nA	$V_{G1S} = \pm 8 V, V_{G2S} = V_{DS} = 0$
Gate 2 cutoff current	I_{G2SS}	—	—	±100	nA	$V_{G2S} = \pm 8 V$, $V_{G1S} = V_{DS} = 0$
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	_	—	-1.0	V	$V_{\rm DS}$ = 10 V, $V_{\rm G2S}$ = 3 V, $I_{\rm D}$ = 100 μA
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	_	—	-1.5	V	$V_{\rm DS}$ = 10 V, $V_{\rm G1S}$ = 3 V, $I_{\rm D}$ = 100 µA
Drain current	I _{DSS}	0	_	10	mA	$V_{DS} = 6 V, V_{G1S} = 0, V_{G2S} = 3 V$
Forward transfer admittance	y _{fs}	17	_	_	mS	$V_{DS} = 6 V, V_{G2S} = 3 V,$ $I_{D} = 10 mA, f = 1 kHz$
Input capacitance	Ciss	—	2.8	3.5	pF	$V_{DS} = 6 V, V_{G2S} = 3 V,$ $I_{D} = 10 mA, f = 1 MHz$
Output capacitance	Coss	_	1.8	2.5	pF	
Reverse transfer capacitance	Crss	—	0.02	—	pF	
Power gain	PG	12	15	_	dB	$V_{DS} = 6 V, V_{G2S} = 3 V,$ $I_{D} = 10 mA, f = 900 MHz$
Noise figure	NF		3.0	4.5	dB	_
Noise figure	NF	_	3.0	4.0	dB	$V_{DD} = 12 \text{ V}, V_{AGC} = 10.5 \text{ V},$ f = 60 MHz
Power gain	PG	27	30	_	dB	$V_{DS} = 6 V, V_{G2S} = 3 V,$ $I_{D} = 10 mA, f = 200 MHz$
Noise figure	NF	_	1.0	2.5	dB	

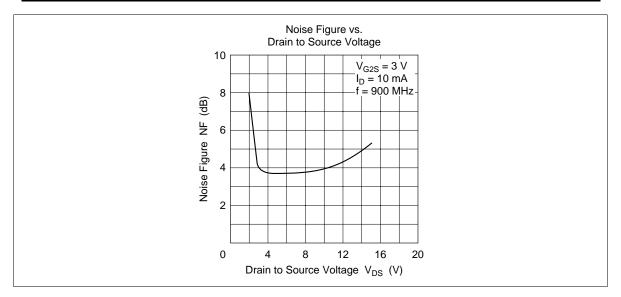
Note: Marking is "IY-".

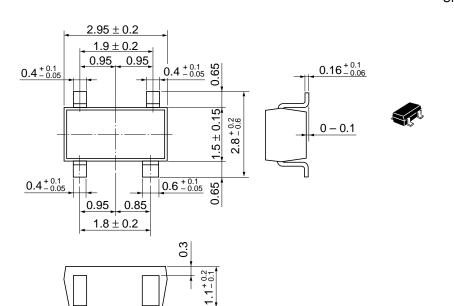




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